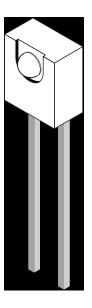
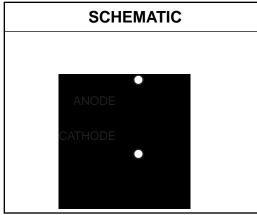
QEE122 QEE123

0.087 (2.22) 0.087 (2.22) 0.000 (5.08) 0.000 (1.27) 0.500 (12.70) 0.500 (12.70) 0.000 (2.54) 0.100 (2.54)



- 1. Dimensions for all drawings are in inches (mm).
- 2. Tolerance of \pm .010 (.25) on all non-nominal dimensions unless otherwise specified.





DESCRIPTION

The QEE12X is a 880 nm AlGaAs LED encapsulated in a medium wide angle, plastic sidelooker package.

FEATURES

- λ = 880 nm
- Package Type = Sidelooker
- Chip Material = AlGaAs
- Matched Photosensor: QSE113
- Medium Wide Emission Angle, 50°
- Package Material: Clear Epoxy
- High Output Power
- · Orange stripe on the top side



QEE122 QEE123

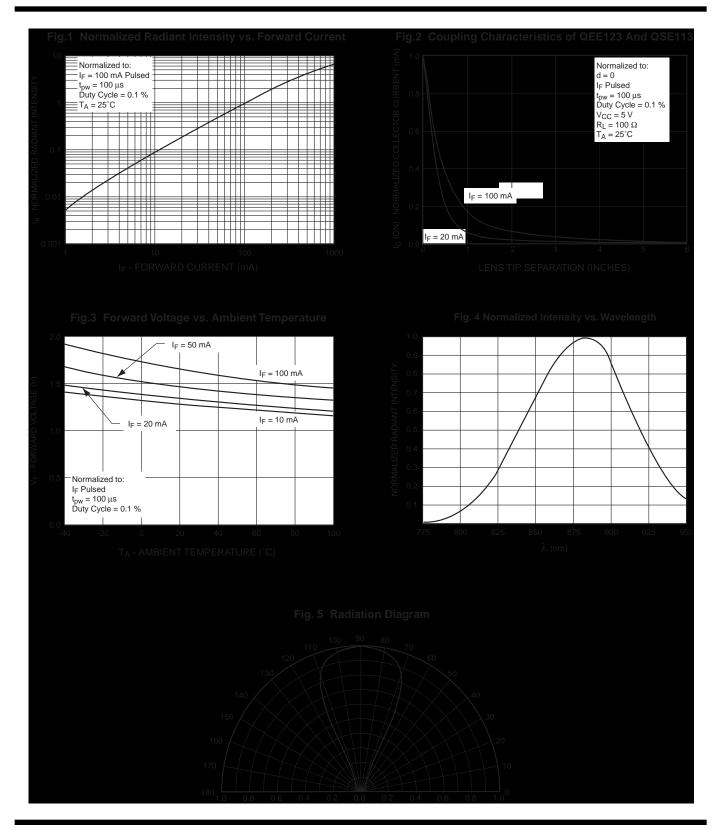
ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise specified)							
Parameter	Symbol	Rating	Unit				
Operating Temperature	T _{OPR}	-40 to + 100	°C				
Storage Temperature	T _{STG}	-40 to + 100	°C				
Soldering Temperature (Iron) ^(2,3,4)	T _{SOL-I}	240 for 5 sec	°C				
Soldering Temperature (Flow) ^(2,3)	T _{SOL-F}	260 for 10 sec	°C				
Continuous Forward Current	I _F	50	mA				
Reverse Voltage	V _R	5	V				
Power Dissipation ⁽¹⁾	P_{D}	100	mW				

NOTES:

- 1. Derate power dissipation linearly 1.33 mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron 1/16" (1.6 mm) minimum from housing

ELECTRICAL / OPTICAL CHARACTERISTICS (T _A =25°C)									
Parameter	Test Conditions	Symbol	Min	Тур	Max	Units			
Peak Emission Wavelength	I _F = 100 mA	λ_{PE}	_	880	_	nm			
Emission Angle	I _F = 100 mA	2⊖1/2	_	50	_	Deg.			
Forward Voltage	$I_F = 100 \text{ mA}, \text{ tp} = 20 \text{ ms}$	V _F	_	_	1.7	V			
Reverse Current	V _R = 5 V	I _R	_	_	10	μA			
Radiant Intensity QEE122	$I_F = 100 \text{ mA}, \text{ tp} = 20 \text{ ms}$	Ι _Ε	4	_	16	mW/sr			
Radiant Intensity QEE123	$I_F = 100 \text{ mA}, \text{ tp} = 20 \text{ ms}$	Ι _Ε	8	_	_	mW/sr			
Rise Time	I _F = 100 mA	t _r	_	800	_	ns			
Fall Time	1 1 - 100 MA	t _f		800	_	ns			

QEE122 QEE123





QEE122 QEE123

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- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.